



Compression Molding System

Model CPM1080series



**Compression molding system
for high-precision WLP/PLP molding processes**

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English

- Ideal for advanced packages such as HBM/2.5D/3D/Chiplet, as well as FOWLP/PLP.
- Enhances mold thickness flatness and achieves higher vacuum levels, resulting in higher quality production.
- Realization of wafer level molding/panel level molding based on proprietary compression technology.
- Both granular/liquid type resin are available in 1 system. ※CPM1080-HP supports either granular or liquid resin. (preselected configuration)
- Features a proprietary uniform resin dispersion and pattern dispensing system.
- Modular concept to adapt to different production quantities.

CPMseries
Wafer typeCPMseries
Panel type

CPM1080-HP

SPECIFICATION

Items		Unit	Description							
Model		—	CPM1080		CPM1080-V		CPM1080-HP			
Workpiece type		—	Panel · Wafer							
Workpiece size	Panel	mm	□150—320							
	Wafer	mm	φ 320 (Max.)							
Molding compound		—	Granular · Liquid (Switchable)				Granular or Liquid (Selectable)			
Machine time		sec	Approximately 88		Approximately 88		Approximately 65			
External dimensions	Number of press modules	module	1	2	1	2	1	2	3	4
	Width	mm	3,910	4,590	3,910	4,590	5,490	6,170	6,850	7,530
	Depth	mm	2,180	2,180	2,180	2,180	2,168	2,168	2,168	2,168
	Height	mm	1,980	1,980	1,980	1,980	1,980	1,980	1,980	1,980
Weight		ton	7.0	10.6	7.0	10.6	10.2	13.8	17.4	21.0
Number of workpieces per cycle		workpiece	1	2	1	2	1	2	3	4
Magazine setting space		—	Panel : Input / Output 2 cassette each Wafer : 2 loadport							
Clamp capacity		kN/(tf)	98.0—784.0/10.0—80.0							
Clamp speed		mm/sec	100 (Max.)							
Release film width		mm	440 (Max.)							

- The figures shown above are based on standard machine specifications.
- The above specification are subject to change without prior notice.
- For special requirements, please consult your local TOWA representative.
- The external dimensions listed are for the granular resin specification.



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